## **ASMT-MY00**

# **1W Power LED Light Source**



# **Data Sheet**







#### **Description**

Avago Technologies' 1W Warm White Power LED is a high performance energy efficient device which can handle high thermal and high driving current. The exposed pad design has excellent heat transfer from the package to the motherboard.

The Warm White Power LED is available in various color temperature ranging from 2600K to 4000K. The product has high Color Rendering Index (CRI) which provides excellent color perception and visual clarity.

The package provides an all in all ease of assembly by automated soldering processes. The low package profile is ideal for assemblies with height constraints.

## **Applications**

- Reading light
- Architectural lighting
- Garden lighting
- Decorative lighting
- Specialty lighting

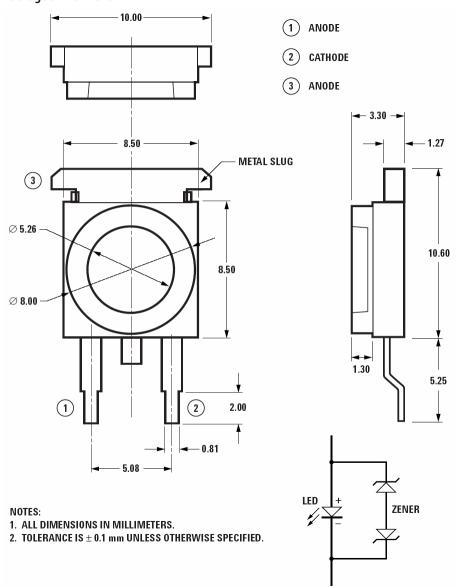
## **Features**

- Available in Warm White color.
- · Energy efficient
- Exposed pad for excellent heat transfer.
- Suitable for reflow soldering process.
- High current operation.
- Long operation life.
- Wide viewing angle.
- Silicone encapsulation
- Non ESD sensitive
- MSL 2A

#### **Specifications**

- InGaN Technology
- 3.6V, 350 mA (Typ.)
- 110 viewing angle

# **Package Dimensions**



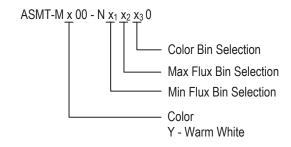
# Device Selection Guide at Junction Temperature $Tj = 25^{\circ}C$

		Luminous Flux, Φv <sup>[1, 2]</sup> (lm)			Test Current	
Color	Part Number	Min	Тур	Max	(mA)	Dice Technology
Warm White	ASMT-MY00	43.0	50.0	73.0	350	InGaN

#### Notes

- 1.  $\Phi_V$  is the total luminous flux output as measured with an integrating sphere at 25ms mono pulse condition.
- 2. Flux tolerance is  $\pm 10\%$

## **Part Numbering System**



## Absolute Maximum Ratings at $T_A = 25$ °C

Parameter	ASMT-MY00	Units
DC Forward Current [1]	350	mA
Peak Pulsing Current [2]	500	mA
Power Dissipation	1400	mW
LED Junction Temperature	110	°C
Operating Ambient Temperature Range	-40 to +85	°C
Storage Temperature Range	-40 to +100	°C
Soldering Temperature	Refer to figure 6	

#### Note:

- 1. DC forward current derate linearly based on Figure 5.
- 2. Pulse condition duty factor = 10%, Frequency = 1kHz.

## Optical Characteristics ( $T_A = 25$ °C)

	Color	Correlated Color Temperature, CCT (Kelvin)		Viewing Angle $2\theta_{1/2}^{[1]}$ (Degrees)	Luminous Efficiency (lm/W)
Part Number		Min	Max	Тур	Тур
ASMT-MY00	Warm White	2600	4000	110	40

#### Notes:

1.  $\theta_{1/2}$  is the off-axis angle where the luminous intensity is 1/2 the peak intensity.

# Electrical Characteristic ( $T_A = 25$ °C)

	Forward Voltage V <sub>F</sub> (Volts) @ I <sub>F</sub> = 350mA		Reverse Voltage V <sub>R</sub> <sup>[1]</sup>	Thermal Resistance $R\theta_{j-ms}$ (°C/W) <sup>[2]</sup>
Dice Type	Тур	Max.		Тур.
InGaN	3.6	4.0	Not recommended	10

#### Note:

- 1. Not designed for reverse bias operation.
- 2.  $R\theta_{j\text{-ms}}$  is Thermal Resistance from LED junction to metal slug.

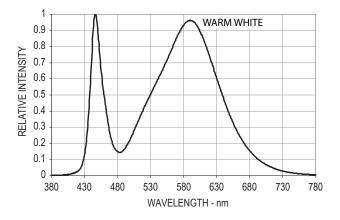


Figure 1. Relative intensity vs. wavelength

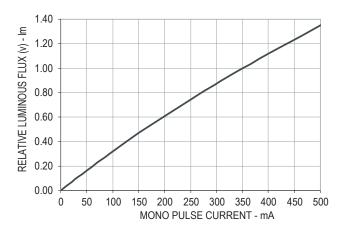


Figure 3. Relative Luminous Flux vs. Mono Pulse Current

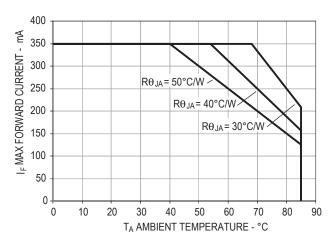


Figure 5. Maximum forward current vs. ambient temperature Derated based on T $_{JMAX}$  = 110°C, R $\Theta_{JA}$  = 30°C/W / 40°C/W and 50°C/W

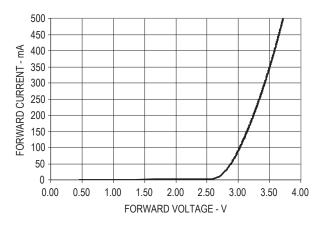


Figure 2. Forward Current vs Forward Voltage

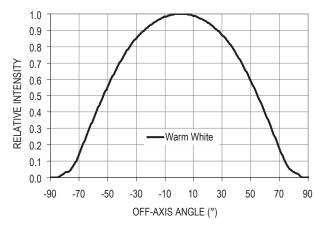
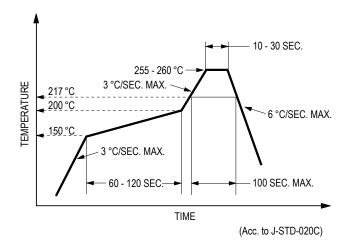


Figure 4. Radiation Pattern



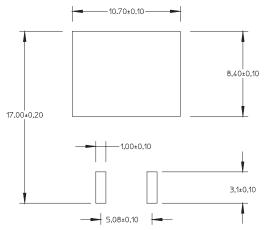
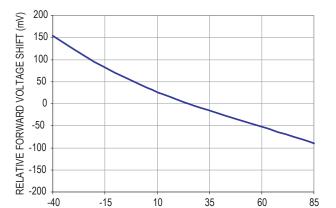


Figure 6. Recommended Reflow Soldering



TEMPERATURE - °C

Figure 7. Recommended soldering land pattern

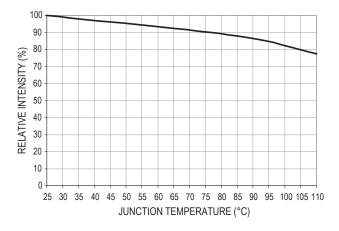


Figure 8. Temperature vs. relative forward voltage shift

Figure 9. Relative LOP vs. junction temperature

## Flux Bin Limit (For reference only) [X<sub>1</sub> X<sub>2</sub>]

	Flux (Im) at 350mA			
Bin	Min	Max		
J	43.0	56.0		
K	56.0	73.0		

Tolerance for each bin limits is  $\pm 10~\%$ 

## Color Bin Selections [X<sub>3</sub>]

Individual reel will contain parts from one full bin only.

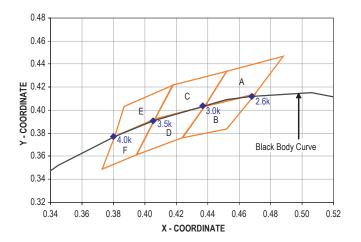
0	Full Distribution
A	A only
В	B only
C	C only
D	D only
E	E only
F	F only
Z	A and B only
Υ	B and C only
W	C and D only
V	D and E only
U	E and F only
Q	A, B and C only
Р	B, C and D only
N	C, D and E only
M	D, E and F only
J	Special Color Bin
1	A, B, C and D only
2	E, F, G and H only
3	B, C, D and E only
4	C, D, E and F only
5	A, B, C, D and E only
6	B, C, D, E, and F only

#### **White Color Limits**

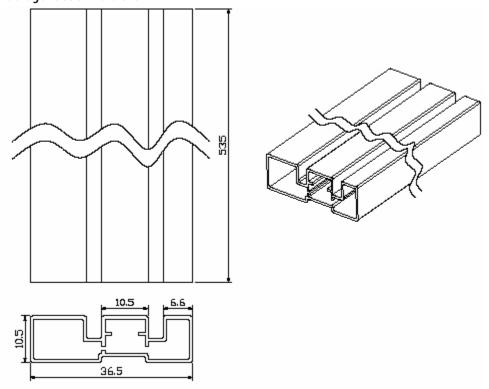
# (Chromaticity Coordinates)

White	Color Limits (Chromaticity Coordinates)					
Bin A	X	0.452 0.434	0.488 0.447	0.470 0.414	0.438 0.403	
Bin B	X	0.438	0.470	0.452	0.424	
Bin C	X	0.403 0.407	0.414	0.384	0.376 0.438	
Bin D	Y	0.393	0.422	0.434	0.403	
DIII D	Y	0.362	0.407	0.438	0.424	
Bin E	X Y	0.381 0.377	0.387 0.404	0.418 0.422	0.407 0.393	
Bin F	X Y	0.373 0.349	0.381 0.377	0.407 0.393	0.395 0.362	

Tolerances ±0.01



## **Package Tube Dimensions**



#### **Handling Precaution**

The encapsulation material of the product is made of silicone for better reliability of the product. As silicone is a soft material, please do not press on the silicone or poke a sharp object onto the silicone. These might damage the product and cause premature failure. During assembly or handling, the unit should be held on the body (white epoxy).

#### **Moisture Sensitivity**

This products is classified as moisture sensitive level 2A

When the bag is opened, parts required to mount within 672 hours of factory conditions  $\leq$ 30°C/60%, and stored at <10% RH.

Devices required bake, before mounting if:

- a) The humidity indicator card is >10% when read at  $23\pm5^{\circ}\text{C}$
- b) The pack has been opened for more than 672 hours. Baking recommended condition: 60±5°C for 20 hours.

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